

IMPROVED SOLDER PASTE CONTAINMENT DEVICE**ABSTRACT**

The invention provides an improved donor substrate for the formation and transfer of solder bumps useful in IC packaging and related interconnect applications. The donor substrate is improved by shaping the solder paste containment region (cavity) so that during reflow, the solder bump is urged to protrude significantly above the surface of the donor substrate, enabling proximity transfer of the solder bump to a receiving substrate.

Figure 1